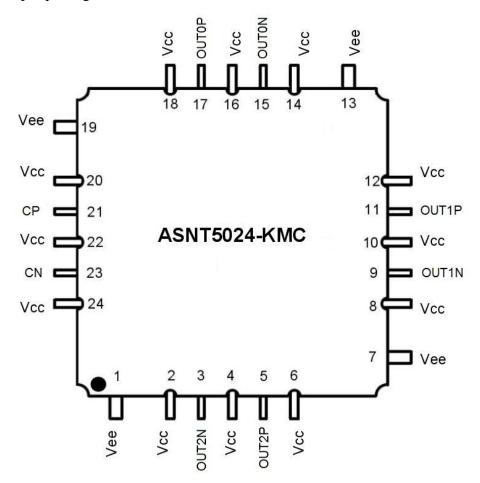
ASNT5024-KMC 28Gbps-17GHz Data/Clock Distributor

- High-speed broadband Data/Clock Amplifier and Splitter for signal distribution.
- Exhibits low jitter and limited temperature variation over industrial temperature range.
- 17*GHz* analog input bandwidth.
- One input signal port and three amplified output signal ports.
- Matched phase delays for all outputs.
- Fully differential CML input interface.
- Fully differential CML output interfaces with 600mV single-ended swing.
- Single +3.3V or -3.3V power supply.
- Power consumption: 780*mW*.
- Fabricated in SiGe for high performance, yield, and reliability.
- Custom CQFP 24-pin package.



DESCRIPTION

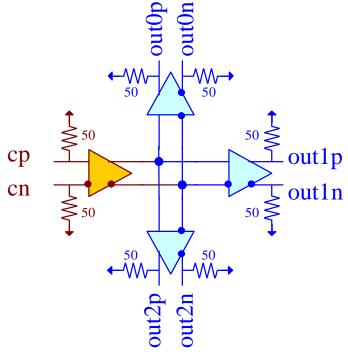


Fig. 1. Functional Block Diagram

The temperature stable ASNT5024-KMC SiGe IC provides active broadband data/clock signal splitting and is intended for use in high-speed measurement / test equipment. The IC shown in Fig. 1 can receive an up to 28Gbps-17GHz data/clock signal and effectively distribute it to three separate phase matched outputs. The part's I/Os support the CML logic interface with on chip 50Ohm termination to "vcc" and may be used differentially, AC/DC coupled, single-ended, or in any combination.

POWER SUPPLY CONFIGURATION

The ASNT5024-KMC can operate with either a negative supply ("vcc" = 0.0V=ground and "vee" = -3.3V), or a positive supply ("vcc" = +3.3V and "vee" = 0.0V=ground). In case of the positive supply, all I/Os need AC termination when connected to any devices with 50Ohm termination to ground. Different PCB layouts will be needed for each different power supply combination.

All the characteristics detailed below assume "vcc" = 0.0V and "vee" = -3.3V.

ABSOLUTE MAXIMUM RATINGS

Caution: Exceeding the absolute maximum ratings shown in Table 1 may cause damage to this product and/or lead to reduced reliability. Functional performance is specified over the recommended operating conditions for power supply and temperature only. AC and DC device characteristics at or beyond the absolute maximum ratings are not assumed or implied. All min and max voltage limits are referenced to ground (assumed "vcc").

Table 1. Absolute Maximum Ratings.

Parameter	Min	Max	Units
Supply Voltage ("vee")		-3.6	V
Power Consumption		0.61	W
RF Input Voltage Swing (SE)		1.0	V
Case Temperature		+90	°C
Storage Temperature	-40	+100	°C
Operational Humidity	10	98	%
Storage Humidity	10	98	%

TERMINAL FUNCTION

TERMINAL		TYPE	DESCRIPTION	
NAME	(NO.)			
	2,4,6,8,10,12	PS	Positive power supply or ground	
14,16	6,18,20,22,24			
vee	1,7,13,19	PS	Ground or negative power supply	
ср	21	Input	Differential CML high-speed signal inputs	
cn	23			
out0p	17	Output	Differential CML high-speed signal outputs	
out0n	15			
out1p	11	Output	Differential CML high-speed signal outputs	
out1n	9			
out2p	5	Output	Differential CML high-speed signal outputs	
out2n	3			



ELECTRICAL CHARACTERISTICS

PARAMETER	MIN	TYP	MAX	UNIT	COMMENTS
vee	-3.1	-3.3	-3.5	V	±6%
vcc		0.0		V	External ground
Ivee		235		mA	
Power		780		mW	
Junction Temp.	-25	50	125	$^{\circ}C$	
Input Data-Clock (c)					
Data rate/Frequency	0.0		28/17	Gbps/GHz	
CM Level	Vcc-0.8	Vcc-0	0.2 Vcc	V	
Swing (Diff or SE)	50	400	1000	mV	Peak-to-peak
Duty Cycle	40%	50%	60%		For clock signal
Out Data-Clock (out)					
Data rate/Frequency	0.0		28/17	Gbps/GHz	
CM Level	Vcc-0.35	Vcc-0.3	3 Vcc-0.25	V	
SE Swing	570	600	630	mV	Peak-to-peak
Rise/Fall Times	15	17	19	ps	20%-80%
Additive Jitter			5	ps	Peak-to-peak
Duty Cycle	45%	50%	55%		For clock signal

PACKAGE INFORMATION

The chip die is housed in a custom 24-pin CQFP package. The package's mechanical information is available on the company's <u>website</u>. Even though the package provides a center heat slug located on the back side of the package to be used for heat dissipation, ADSANTEC does <u>NOT</u> recommend for this section to be soldered to the board. If the customer wishes to solder it, it should be connected to the "vcc" plain, which is ground for the negative supply or power for the positive supply.

The part's identification label is ASNT5024-KMC. The first 8 digits of the name before the underscore identify the bare die including general circuit family, fabrication technology, specific circuit type, and part version while the 3 digits after the underscore represent the package's manufacturer, type, and pin out count.

This device complies with the Restriction of Hazardous Substances (RoHS) per EU 2002/95/EC for all six substances.



REVISION HISTORY

Revision	Date	Changes
3.1	2-2012	Revised Pinout drawing
		Revised Power Supply Configuration section
		Revised Package Information section
3.0	1-2012	Added Power Supply Configuration text
		Added Absolute Maximum Ratings table
		Revised Electrical Characteristics section
		Revised Package Information section
2.0	2-2009	Revised Electrical Characteristics section
		Revised Package Information section
1.0	1-2009	First release